

WHAT IS CLAIMED IS:

1. A polishing body having a polishing part that is formed by solidifying an aqueous dispersion wherein a matrix material and abrasive are dispersed and contained respectively.
2. The polishing body according to Claim 1, wherein the polishing body is used for the polishing of semiconductors.
3. A polishing body having a polishing part that is formed by solidifying an aqueous dispersion containing dispersed composite particles wherein abrasive is attached to a matrix material.
4. The polishing body according to Claim 3, further a matrix material and/or abrasive are dispersed and contained in said aqueous dispersion.
5. The polishing body according to Claim 3, wherein the respective zeta potentials of said matrix material and said abrasive are opposite in sign and the difference of said zeta potentials is 5mV or more.
6. The polishing body according to Claim 3, wherein the polishing body is used for the polishing of semiconductors.
7. A polishing body having a polishing part that is formed by solidifying an aqueous dispersion wherein a matrix material comprised of a crosslinkable polymer and abrasive are dispersed and contained respectively, and a polishing part that has a crosslinked structure.
8. The polishing body according to Claim 7, wherein the

polishing body is used for the polishing of semiconductors.

9. A polishing body having a polishing part that is formed by solidifying an aqueous dispersion containing dispersed composite particles wherein abrasive is attached to a matrix material comprised of a crosslinkable polymer, and a polishing part that has a crosslinked structure.

10. The polishing body according to Claim 9, wherein the respective zeta potentials of said matrix material and said abrasive are opposite in sign and the difference of said zeta potentials is 5mV or more.

11. The polishing body according to Claim 9, wherein the polishing body is used for the polishing of semiconductors.